

### **STPS50U100C**

## Ultralow forward voltage power Schottky rectifier

#### **Features**

- Ultralow forward voltage drop
- High current capability
- High frequency operation
- ECOPACK®2 compliant components

#### **Description**

The STPS50U100C is a dual power Schottky diode rectifier, suited for high frequency switch mode power supply.

Featuring an ultralow forward voltage drop, this device, packaged in TO-220AB and I²PAK, is intended to be used in notebook, game station and desktop adaptors as well as server SMPS. It has been especially designed to help power supply manufacturers meet the recently introduced worldwide efficiency standards.

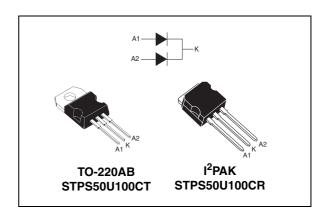


Table 1. Device summary

Symbol	Value		
I <sub>F(AV)</sub>	2 x 25 A		
V <sub>RRM</sub>	100 V		
V <sub>F(TYP)</sub> @ 25 A @ 125 °C	0.64 V		
T <sub>j (max)</sub>	150 °C		

Characteristics STPS50U100C

#### 1 Characteristics

Table 2. Absolute ratings (limiting values per diode at 25 °C, unless otherwise specified)

Symbol	Parameter	Value	Unit		
$V_{RRM}$	Repetitive peak reverse voltage			100	V
I <sub>F(RMS)</sub>	Forward rms current			50	Α
I <sub>F(AV)</sub>	Average forward current, $\delta = 0.5$	erage forward current, $\delta$ = 0.5 $T_{C}$ = 120 °C $T_{C}$ Per diode $T_{C}$ = 105 °C Per device		25 50	Α
I <sub>FSM</sub>	Surge non repetitive forward current	$t_p = 10 \text{ ms, ha}$	250	Α	
T <sub>stg</sub>	Storage temperature range			-65 to + 150	°C
T <sub>j</sub>	Maximum operating junction temperature <sup>(1)</sup>			150	°C

<sup>1.</sup>  $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$  condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter		Value	Unit
R <sub>th (j-c)</sub>	Junction to case	diode device	1.3 0.9	°C/W
R <sub>th (c)</sub>	Coupling		0.45	°C/W

When the diodes 1 and 2 are used simultaneously:  $\Delta T_j(\text{diode 1}) = P(\text{diode1}) \ x \ R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \ x \ R_{th(c)}$ 

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
		T <sub>j</sub> = 25 °C	V <sub>R</sub> = 70 V	-	15	-	μΑ
I_		T <sub>j</sub> = 125 °C		-	10	-	mA
I <sub>R</sub>		T <sub>j</sub> = 25 °C	$V_R = V_{RRM}$	-	30	200	μΑ
		T <sub>j</sub> = 125 °C		-	15	40	mA
V <sub>F</sub> Forward	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 5 A	-	0.48	-	
		T <sub>j</sub> = 125 °C		-	0.38	-	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 15 A	-	0.58	-	V
		T <sub>j</sub> = 125 °C		-	0.54	-	V
		T <sub>j</sub> = 25 °C	- I <sub>F</sub> = 25 A	-	0.67	0.73	
		T <sub>j</sub> = 125 °C		-	0.64	0.7	

To evaluate the conduction losses use the following equation:

$$P = 0.475 \text{ x I}_{F(AV)} + 0.009 \text{ I}_{F}^{2}_{(RMS)}$$

STPS50U100C Characteristics

Figure 1. Average forward power dissipation Figure 2. versus average forward current (per diode)

Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

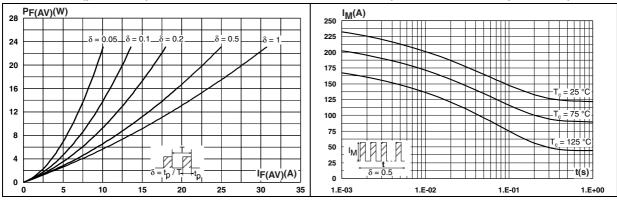


Figure 3. Reverse leakage current versus reverse voltage applied (typical values, per diode)

Figure 4. Average forward current versus ambient temperature ( $\delta$  = 0.5, per diode)

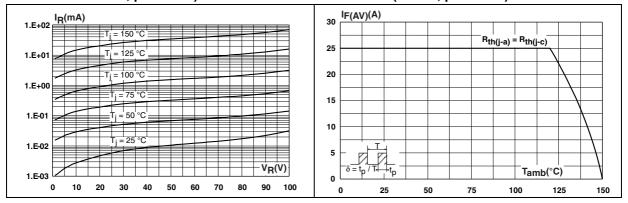
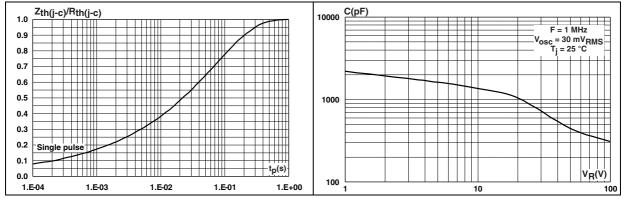


Figure 5. Relative variation of thermal impedance junction to case versus pulse duration

Figure 6. Junction capacitance versus reverse voltage applied (typical values, per diode)



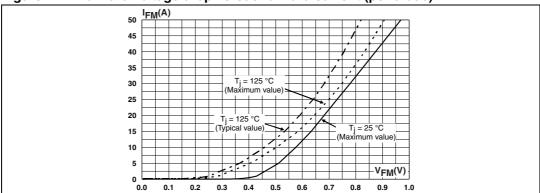
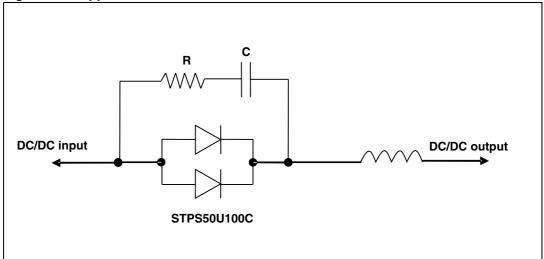


Figure 7. Forward voltage drop versus forward current (per diode)

## 2 Application information

It is mandatory to ensure a peak reverse voltage below the  $V_{RRM}$  absolute rating. Therefore, it is recommended to use a RC clamping snubber circuit in parallel with the STPS50U100C device.

Figure 8. Application schematic

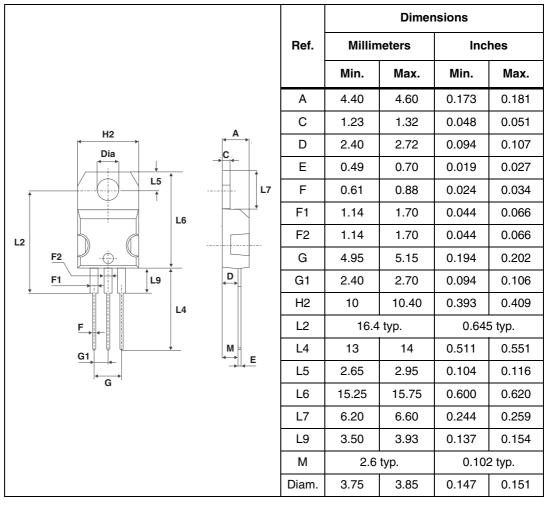


#### 3 Package information

- Epoxy meets UL94,V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.4 to 0.6 N⋅m

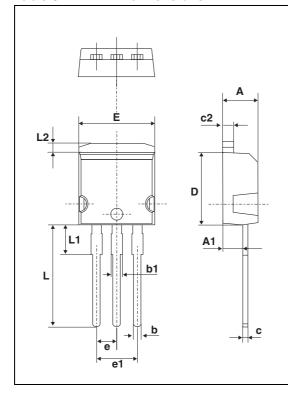
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

Table 5. TO-220AB dimensions



Package information STPS50U100C

Table 6. I<sup>2</sup>PAK dimensions



	Dimensions				
Ref.	Millim	neters	Inches		
	Min. Max.		Min.	Max.	
Α	4.40	4.60	0.173	0.181	
A1	2.40	2.72	0.094	0.107	
b	0.61	0.88	0.024	0.035	
b1	1.14	1.70	0.044	0.067	
С	0.49	0.70	0.019	0.028	
c2	1.23	1.32	0.048	0.052	
D	8.95	9.35	0.352	0.368	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
Е	10	10.40	0.394	0.409	
L	13	14	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L2	1.27	1.40	0.050	0.055	

## 4 Ordering information

 Table 7.
 Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS50U100CT	STPS50U100C	TO-220AB	2.23 g	50	Tube
STPS50U100CR	STPS50U100C	I <sup>2</sup> PAK	1.49 g	50	Tube

# 5 Revision history

Table 8. Document revision history

Date	Revision	Changes
17-Nov-2009	1	First release.

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